

Product Data Sheet

Liquid-Dispensed Silicone Thermal Pad / GapFiller SilCool TIA265GF (XE14-D0034)

SilCool TIA265GF (XE14-D0034) is a 2-component, soft, thermally conductive silicone material that is designed to dissipate heat from electronic devices. Its non-slumping pasty consistency provides physical stability for optimized processing. TIA26GF can be used as liquid dispensed alternative to pre-fabricated Thermal Pads, for a broad array of thermal designs in electronic applications.

KEY FEATURES

- High thermal conductivity
- Fast, low temperature cure
- Convenient 1:1 mix ratio by weight
- Retains softness after cure to contribute to stress relief during thermal cycling
- Good slump resistance (stays in place)
- Repairable
- Typical Operating Temp Range -40° to 150°C

TYPICAL PROPERTIES

UNCURED PROPERTIES	TIA 265GF XE14-D0034 (A)	TIA 265GF XE14-D0034 (B)
Appearance (Part A & B)	pink	pale pink
Viscosity *1 Pa·s	230	225
Mix ratio by weight	1 : 1	
Viscosity *1 after mixing Pa·s	184	
Thixo Index	2.6	
Work Life @ 23°C Hours	1	
Cure conditions Hours		
@ 70°C	1	
@ 23°C	24	
CURED PROPERTIES (1 hour @ 70°C)		
Appearance	pink	
Density (23°C) g/cm ³	3.26	
Thermal conductivity *2 W/m·K	6.7	
Thermal resistance *3 mm ² ·K/W	33.8	
Minimum bond line thickness μm	200	
Hardness (Type E)	27	
Hardness (Shore 00)	54	
Tensile strength MPa	0.025	
Elongation %	60	
Dielectric strength kV/mm	14	
Low volatile (D ₄ -D ₁₀) ppm	100	

*1: Plate-plate rheometer / *2: Hot disk method / *3: ASTM 5470

Typical properties / These values are not intended for use in preparing specifications.

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TYPICAL APPLICATIONS

Thermal interface for electronic components in Automotive, Consumer, Telecommunication, Lighting and Industrial applications

GENERAL CONSIDERATIONS:

While the typical operating temperature for silicone materials ranges from -45°C to 150°C, the long-term maintenance of its initial properties is dependent upon design related stress considerations, substrate materials, frequency of thermal cycles, and other factors.

HANDLING AND SAFETY

- Materials such as water, sulfur, nitrogen compounds, organic metallic salts, phosphorus compounds, etc. contained in the surface of the substrate can inhibit curing. A sample patch should always be conducted before proceeding to determine compatibility.
- Wear eye protection when handling uncured rubber as it can irritate eyes. In case of eye contact, immediately flush eyes well with water and contact a physician.
- Maintain adequate ventilation in the work place at all times.

STORAGE AND PACKAGING

- Store in a cool, dry place out of direct sunlight
- Keep out of the reach of children
- Packaging: 400cc cartridge, 20Oz SEMCO Cartridge, 20l plastic pail

OPTION for GLASS BEADS

- Glass Bead versions for BLT control can be made available upon request (typically sizes 180 μ and 250 μ)

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